

Type number	Package	Package description	Total product weight
74AHC3GU04DC	SOT765-1	VSSOP8	9.31397 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator	
		MSL	PPT	MPPT	MSL	PPT	MPPT				
935275124125	9	1	260	30 s	1	240	20 s	3	Suzhou, China; Nijmegen, Netherlands; Ayutthaya, Thailand; Bangkok, Thailand	IMG	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.80500	80.50000	8.64293
		Polymer	Resin system	Proprietary	0.19500	19.50000
			subTotal		1.00000	100.00000
Die	Doped silicon	Silicon (Si)	7440-21-3	0.09916	100.00000	1.06466
			subTotal	0.09916	100.00000	1.06466
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	2.33928	97.47000	25.11582
		Iron (Fe)	7439-89-6	0.05760	2.40000	0.61843
		Phosphorous (P)	7723-14-0	0.00072	0.03000	0.00773
		Zinc (Zn)	7440-66-6	0.00240	0.10000	0.02577
		subTotal		2.40000	100.00000	25.76775
Mould Compound	Filler	Misc. Silica compounds (generic)	14808-60-7	4.48000	80.00000	48.09979
		Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.09520	1.70000
		Misc. Bromine compounds (generic)	7726-95-6	0.07280	1.30000	0.78162
	Polymer	Epoxy resin system	Proprietary	0.95200	17.00000	10.22121
		subTotal		5.60000	100.00000	60.12474
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00170	1.00000	0.01825
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.16490	97.00000	1.77046
		Palladium (Pd)	7440-05-3	0.00340	2.00000	0.03650
			subTotal		0.17000	100.00000
Wire	Pure metal	Gold (Au)	7440-57-5	0.04436	99.00000	0.47630
		Palladium (Pd)	7440-05-3	0.00045	1.00000	0.00481
		subTotal		0.04481	100.00000	0.48111

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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